

FIG. 2

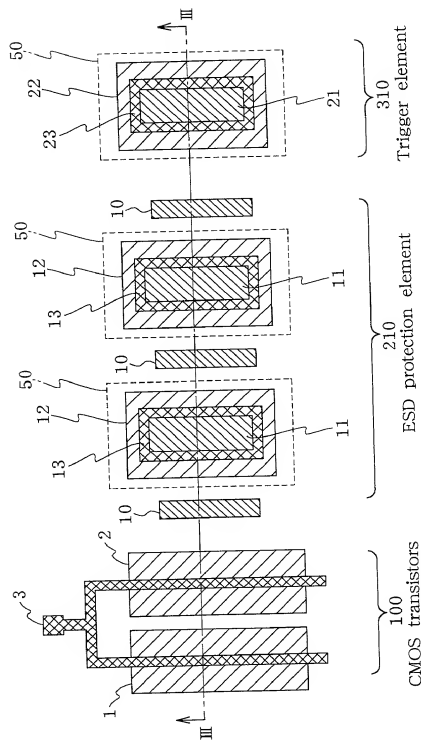


FIG. 3

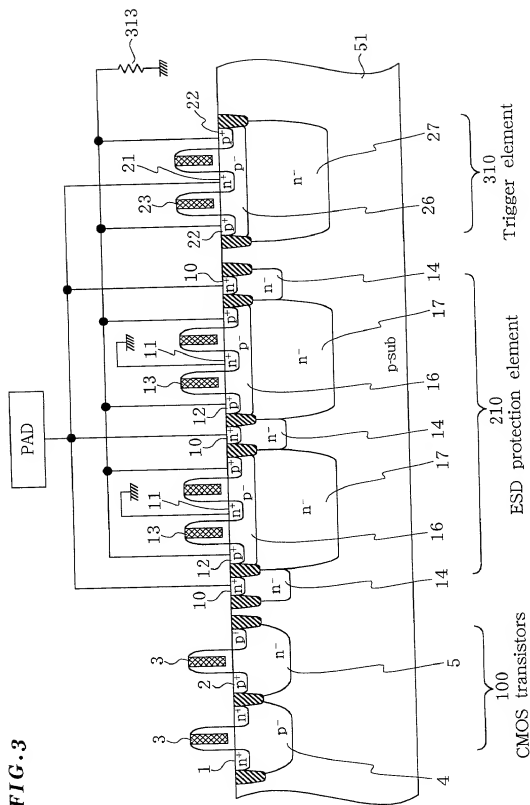


FIG. 4

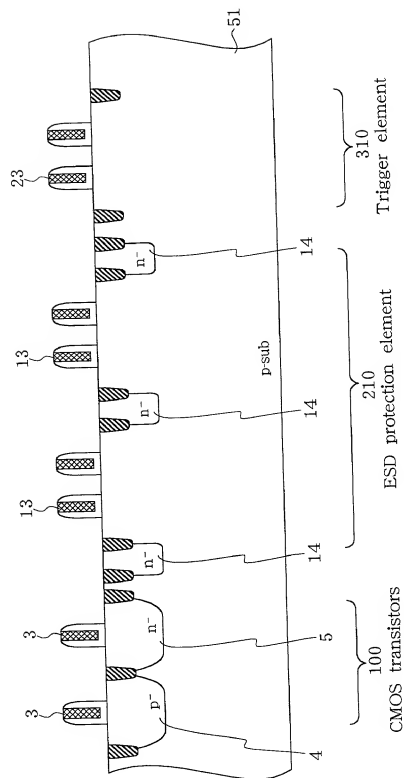


FIG. 5

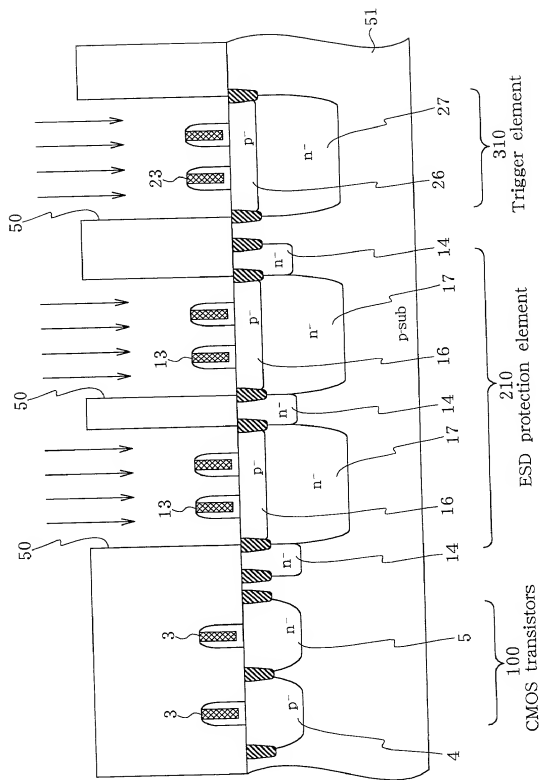
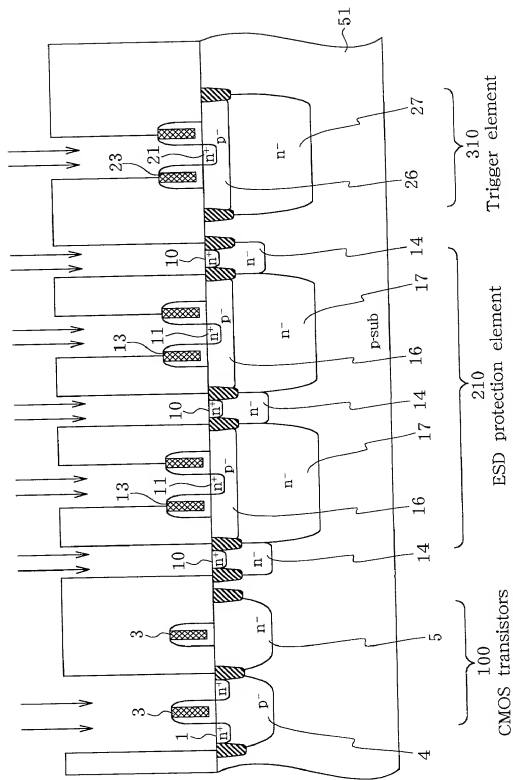


FIG. 6



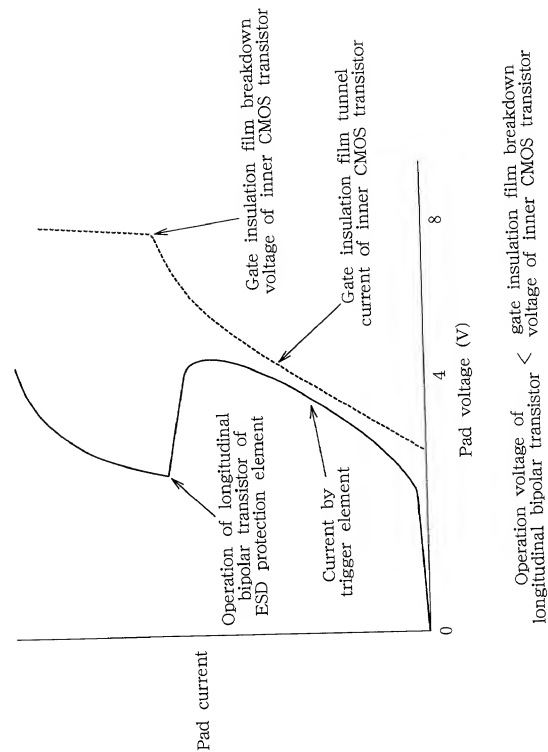


FIG. 8

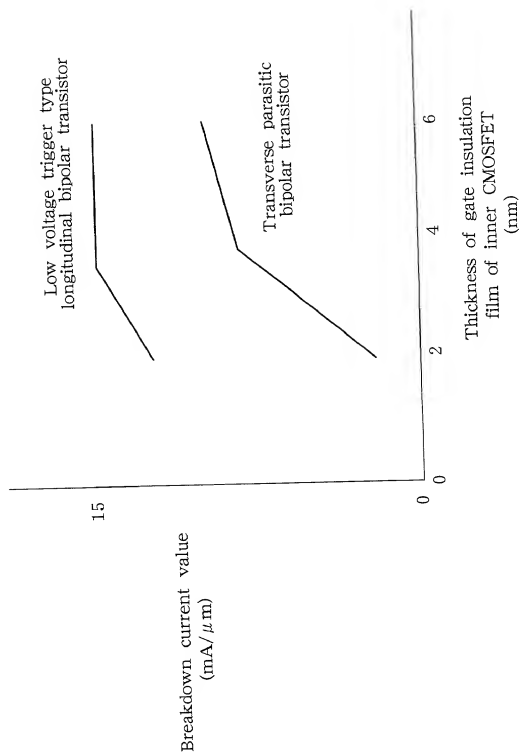


FIG. 9

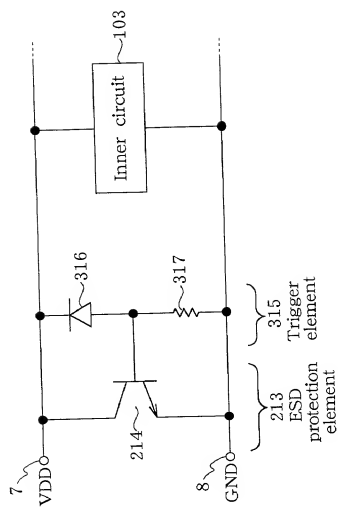


FIG. 10

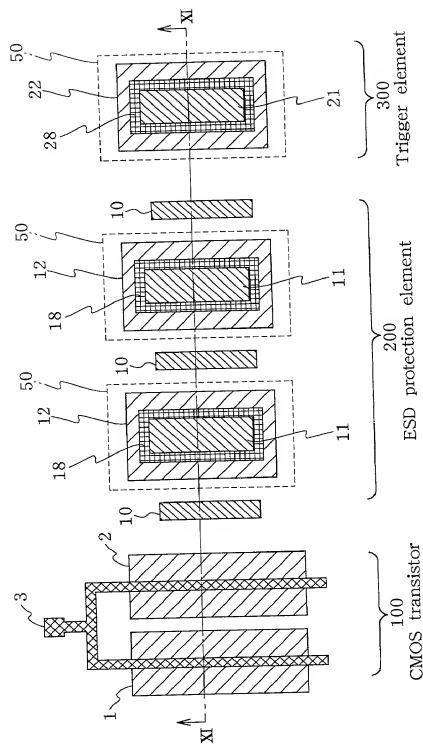


FIG. 11

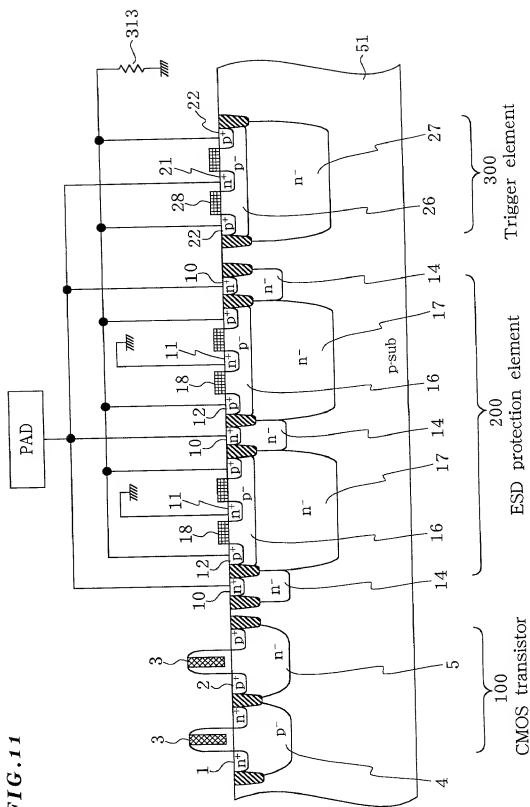


FIG. 12

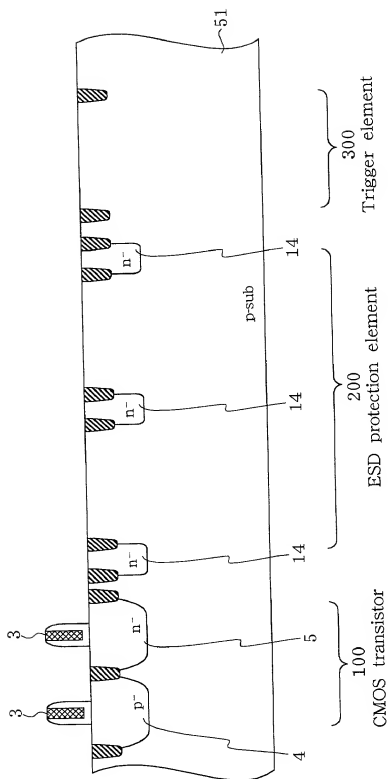


FIG. 13

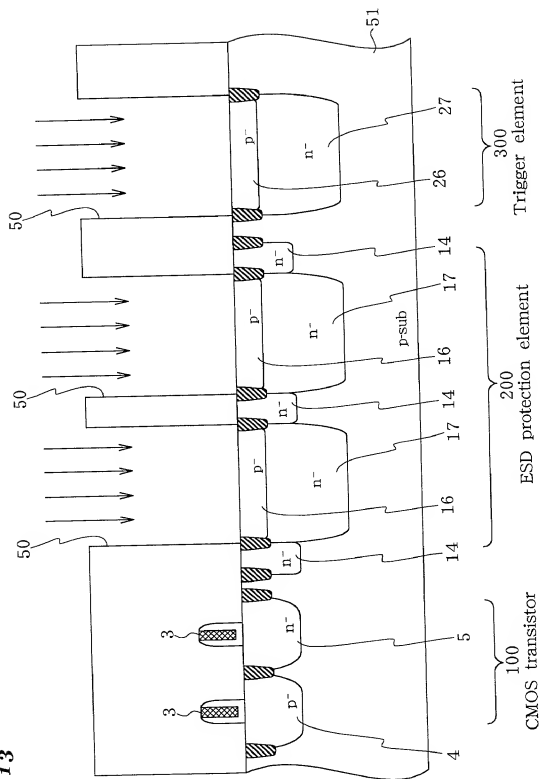


FIG. 14

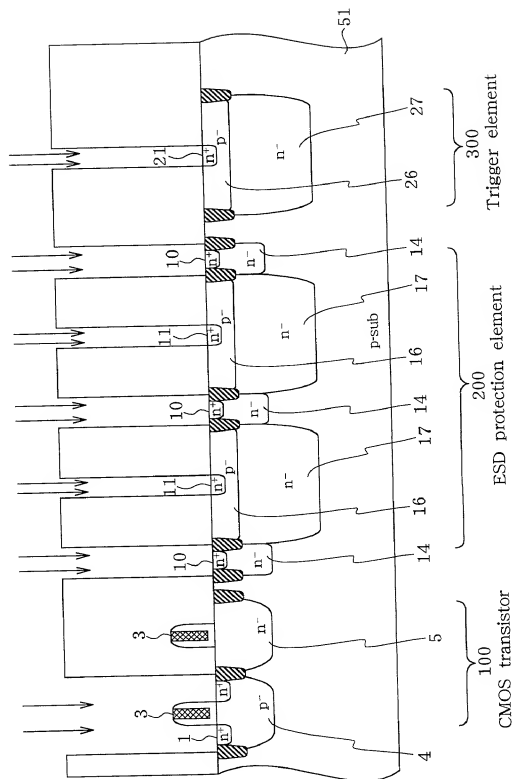


FIG. 16

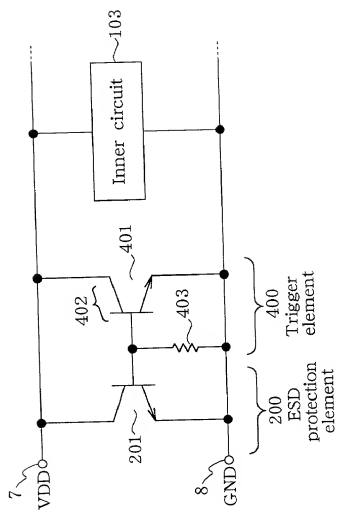


FIG. 17

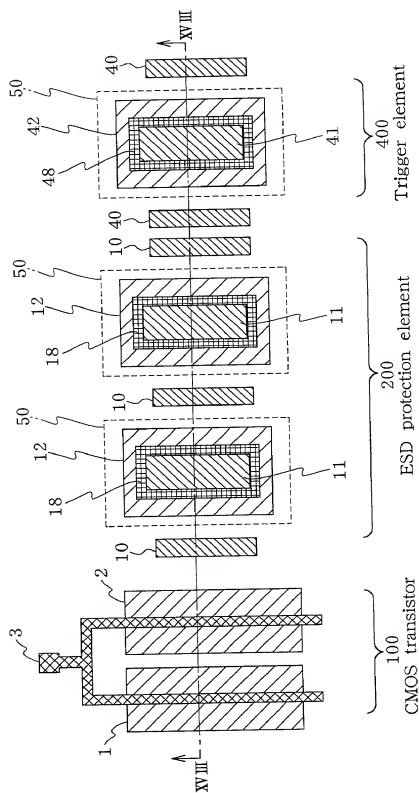


FIG. 18

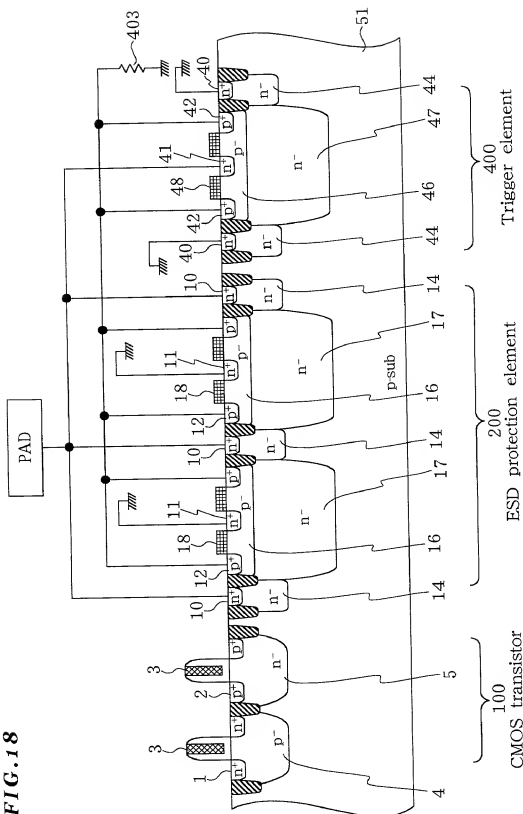


FIG. 19

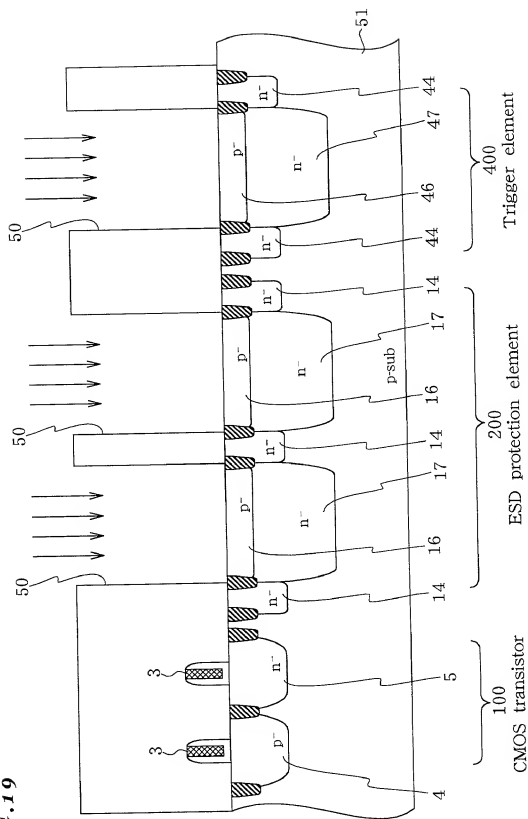


FIG. 21

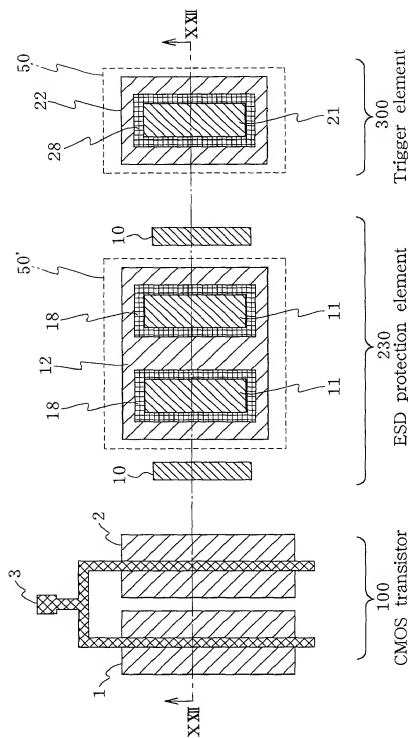


FIG. 22

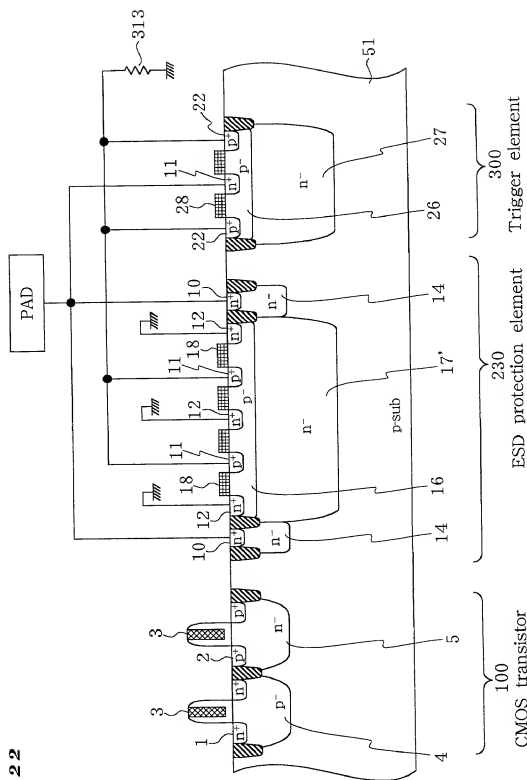


FIG. 23

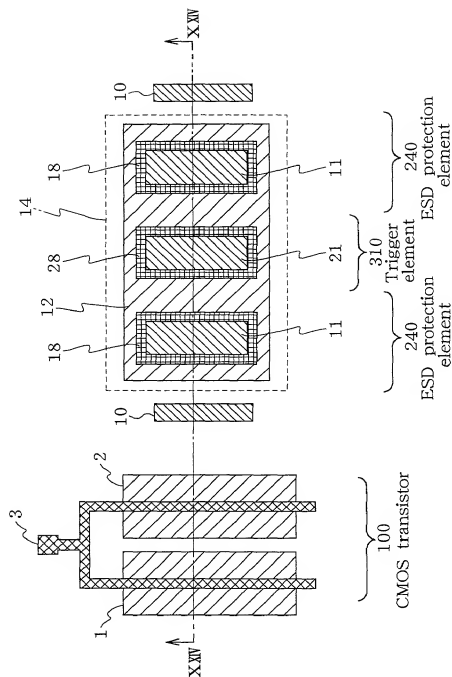


FIG. 24

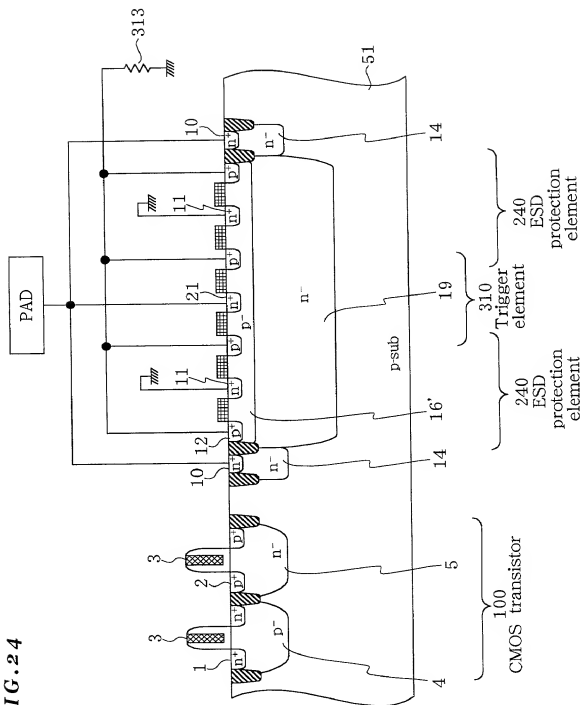


FIG. 25

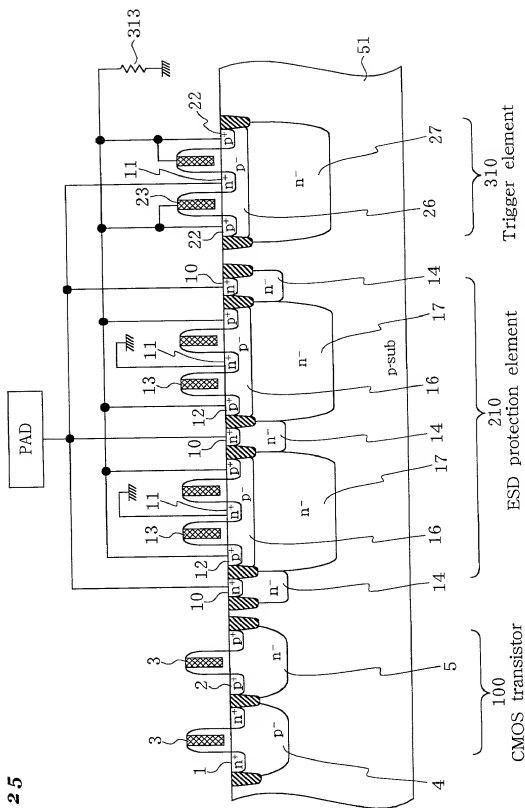


FIG. 26

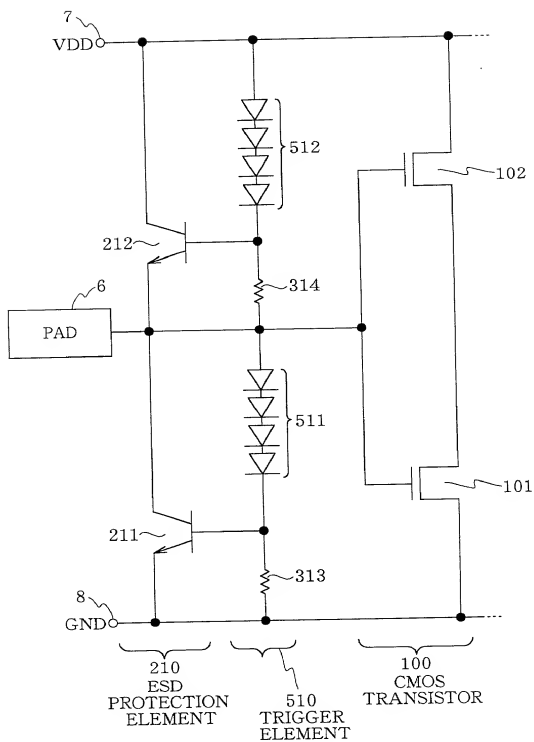
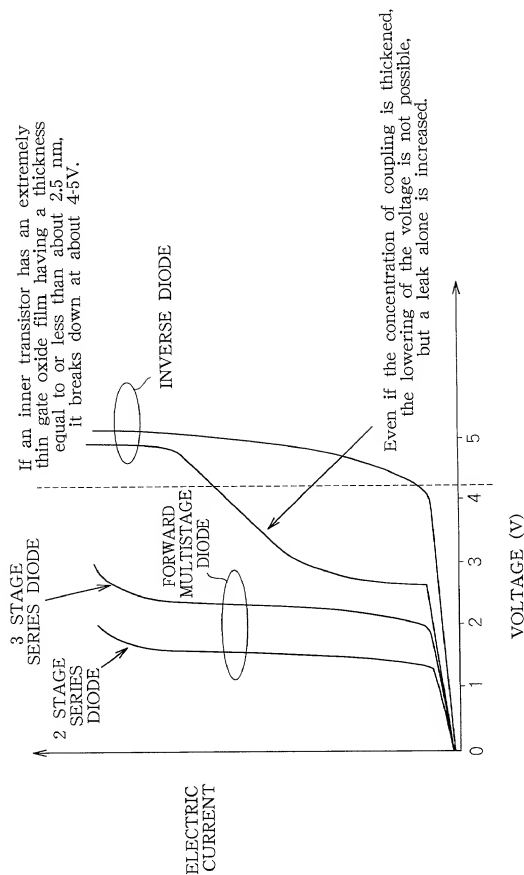


FIG. 28

COMPARISON OF FORWARD SERIES CONNECTION DIODE
AND INVERSE DIODE

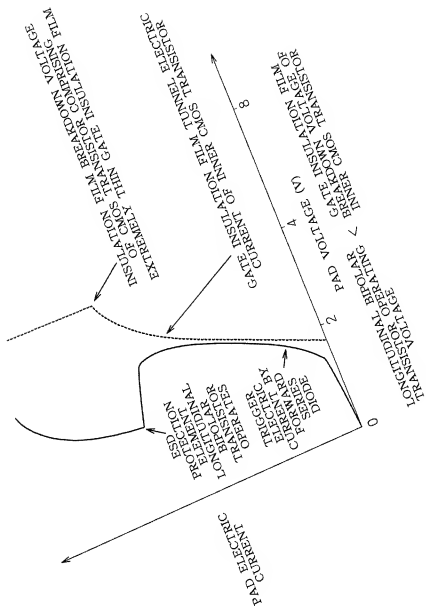


FIG. 29

FIG. 30

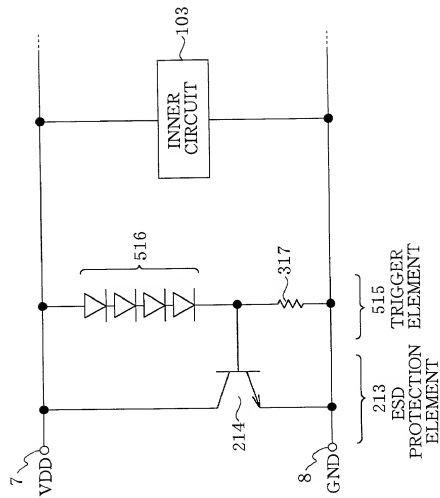


FIG. 31

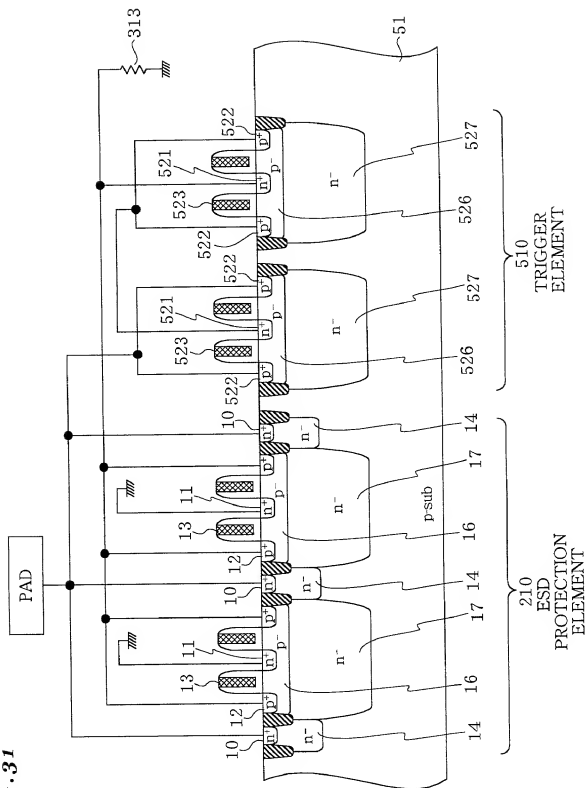


FIG. 32(a)

DIODE COMPRISING
p-LAYER/ n well
FABRICATED BY
EXISTING CMOS PROCESS

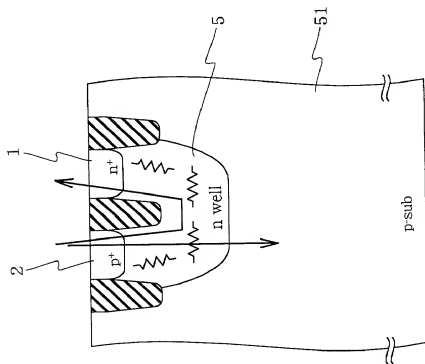


FIG. 32(b)
DIODE UTILIZING ONE PORTION
OF LONGITUDINAL
BIPOLAR TRANSISTOR

DIODE UTILIZING ONE PORTION OF LONGITUDINAL BIPOLAR TRANSISTOR

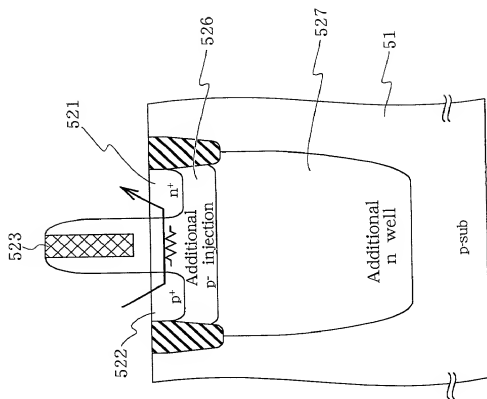


FIG.33

